おかげさまで 80周年

SMIC

AUTOMOTIVE WORLD 2019 INVITATION

BEYOND CONNECTION

– SMIC MOBILITY, INSIGHT CONNECTONS ! –

Int'l Automotive Electronics Technology Expo

Dear Sirs / Madams,

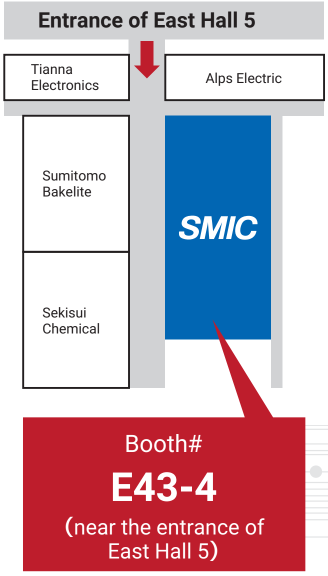
We wish to express our gratitude for your prosperity and continued support.
We will exhibit at the 11th International Automotive Electronics Technology Expo to be held in the 48th Nepcon Japan at Tokyo Big Sight, for three days during January 16th and January 18th, 2019.
In this time, the automotive industry is facing a once in a century transformation. We consider EV, Power, IoT, and AI to be significant business fields and are going to introduce our solder materials and FA equipment to assist our customers.

We look forward to seeing you at our booth soon!
Best regards,

Senju Metal Industry Co., Ltd.
President Ryoichi Suzuki

Access

● Rinkai Line **Kokusai-Tenjijo Sta.**	Approx. 7 min. walk
● Yurikamome **Kokusai-Tenjijo-Seimon Sta.**	Approx. 3 min. walk



Booth#
E43-4
(near the entrance of East Hall 5)

BEYOND CONNECTION – SMIC MOBILITY, INSIGHT CONNECTONS ! –

11th

CAR-ELE JAPAN

Int'l Automotive Electronics Technology Expo

Date January 16 (Wed) - 18 (Fri), 2019
Time 10:00 a.m. - 6:00 p.m. (5:00 p.m. on the last day)
Venue Tokyo Big Sight, Tokyo, Japan
Booth# E43-4 (near the entrance of East Hall 5)

About the Displays

Material Solutions

- Low temperature soldering materials
- Solder preforms
- Residue crack resistance solder paste

Machine Solutions

- Mask Dip Soldering Machine LPD-2019M
- ECOPASCAL SPF2-400 (with SK options)

Presentations at Our Booth

Products Proposal on V2X with Focus on EV

- Proposal on AI and sensing technology
  ～ Low temperature materials ～
- Proposal on renewable power
  ～ Solder preforms ～

SPECIAL SMIC Efforts Towards EV and Next V2X

- Adaptive approach for global EV trend
  International Business Div.
  Divisional General Manager **Satoru Akita**
- Development of solder materials for V2X era
  R&D Engineering Div. Solder Technical Center
  General Manager **Masato Shimamura**

Seminars at Other Locations

January 16th, Wed. 9:30 a.m. – 12:00 p.m.

Location: Conference Tower

NEPCON Conference / Technical Session

Title High Reliability Solder Material for Automotive

Speaker R&D Engineering Div. Solder Technical Center
Executive Researcher **Syunsaku Yoshikawa**

＊Registration is required in advance on the organizer's website

January 18th, Fri. 12:20 p.m. – 1:20 p.m.

Location: East Hall 2nd Floor Meeting Room

Exhibitors' Presentation

Title New Soldering Approach for the Era of EV & ADAS

Speaker R&D Engineering Div. Solder Technical Center
General Manager **Masato Shimamura**

＊No sign-up or registration fee required, but limited for the first 50 visitors

Details of the location will be posted on the organizer's website by a week before the exhibition

SENJU METAL INDUSTRY CO.,LTD.
CSR & Public Relations Div.
Senju Hashido-cho 23, Adachi-ku, Tokyo 120-0038
Phone: (81)3-3888-5151 Fax: (81)3-3870-5501
www.senju.com

SMIC